

Title of the Invention

POLYAMIDE RESIN COMPOSITION AND MOLDED ARTICLE

ABSTRACT

Disclose is a polyamide resin composition having excellent heat resistance, heat aging resistance and mechanical physical properties, which is produced by incorporating a specified aromatic secondary amine compound and a specified organic sulfur based compound into a polyamide composed of a diamine unit containing a paraxylylenediamine unit as a major component and a dicarboxylic acid unit containing a linear aliphatic dicarboxylic acid unit having from 6 to 18 carbon atoms as a major component.

No Figure